



15A 700V N-CHANNEL POWER MOSFET

Description

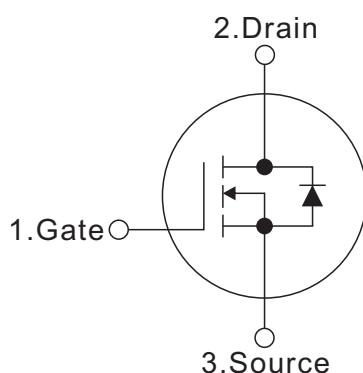
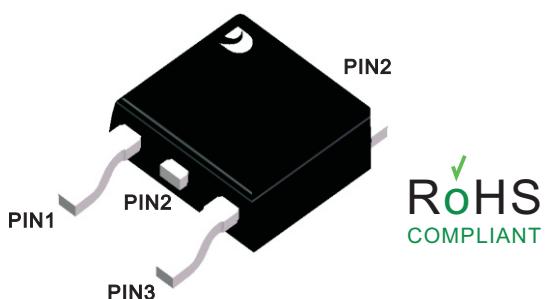
The power MOSFET using **super junction** technology that can realize very low on-resistance and gate charge. It will provide much high efficiency by using optimized charge coupling technology. These user friendly devices give an advantage of Low EMI to designers as well as low switching loss.

Features

- $R_{DS(ON)} \leq 0.28 \Omega$ @ $V_{GS}=10V$, $I_D=7.5A$
- Fast switching capability
- Low On-Resistance
- 100% Avalanche tested
- 100% ΔV_{DS} tested

Mechanical data

- Case: TO-252W
- Approx. Weight: 0.33g (0.012oz)
- RoHS compliant
- Case Material: "Green" molding compound, UL flammability classification 94V-0, "Halogen-free".



Absolute Maximum Ratings (Ta=25°C, Unless Otherwise Specified)

Parameter	Symbols	Ratings	Units
Drain-Source Voltage	V_{DSS}	700	V
Gate-Source Voltage	V_{GSS}	± 30	V
Continuous Drain Current $T_c=25^\circ C$ $T_c=100^\circ C$	I_D	15 11	A
Pulsed Drain Current (Note 2)	I_{DM}	60	A
Avalanche Energy Single Pulsed (Note 3)	E_{AS}	198	mJ
Power Dissipation ($T_c = 25^\circ C$)	P_D	62.5	W
Operating junction and storage temperature	$T_{J,T_{STG}}$	-55 ~ +150	°C

Notes:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.
Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- 2.Repetitive Rating: Pulse width limited by maximum junction temperature.
3. $I_{AS}=6.3A, L=10mH, V_{DD}=50V, R_G=25\Omega$, Starting $T_J=25^\circ C$

Thermal Resistance

Parameter	Symbols	Ratings	Units
Thermal resistance, junction – case.	R_{thJC}	1.5	°C/W
Thermal resistance, junction – ambient(min. footprint)	R_{thJA}	63	°C/W



Electrical Characteristics (Ta=25°C, Unless Otherwise Specified)

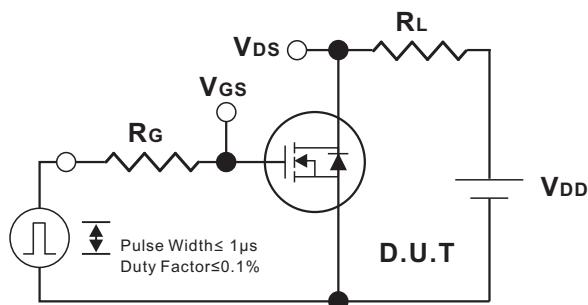
Parameter	Symbols	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	700			V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =700V, V _{GS} =0V			1.0	μA
Gate- Source Leakage Current	Forward	I _{GSS}	V _{GS} =30V, V _{DS} =0V		100	nA
	Reverse		V _{GS} =-30V, V _{DS} =0V		-100	
On Characteristics						
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _D =250μA	3.5		4.5	V
Static Drain-Source On-State Resistance	R _{D(S)} (ON)	V _{GS} =10V, I _D =7.5A		0.25	0.28	Ω
Transconductance	g _{fs}	V _{DS} =15V, I _D =2A		4.8		S
Dynamic Characteristics						
Input Capacitance	C _{ISS}	V _{DS} =25V, V _{GS} =0V, f=1.0MHz		1173		pF
Output Capacitance	C _{OSS}			921		pF
Reverse Transfer Capacitance	C _{rss}			13.4		pF
Gate resistance	R _G			5		Ω
Switching Characteristics						
Total Gate Charge (Note 1)	Q _G	V _{DS} =480V, V _{GS} =10V, I _D =15A (NOTE1,2)		28		nC
Gate-Source Charge	Q _{GS}			8		nC
Gate-Drain Charge	Q _{GD}			13		nC
Turn-On Delay Time (Note 1)	t _{D(ON)}	V _{DS} =300V, I _D =15A R _G =25Ω, V _{GS} =10V (NOTE1,2)		24		ns
Turn-On Rise Time	t _R			45		ns
Turn-Off Delay Time	t _{D(OFF)}			90		ns
Turn-Off Fall Time	t _F			49		ns
Drain-Source Diode Characteristics And Maximum Ratings						
Maximum Body-Diode Continuous Current	I _S				15	A
Drain-Source Diode Forward Voltage (Note 1)	V _{SD}	I _{SD} =15A, V _{GS} =0V			1.4	V
Reverse Recovery Time (Note 1)	t _{rr}	I _F =15A di/dt=100A/us		340		ns
Reverse Recovery Charge	Q _{rr}			5		uC

Notes:

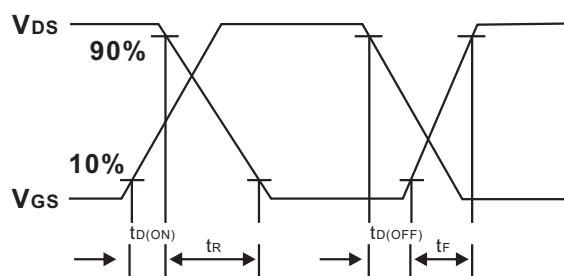
1. Pulse Test: Pulse width ≤ 300μs, Duty cycle ≤ 2%.
2. Essentially independent of operating temperature.



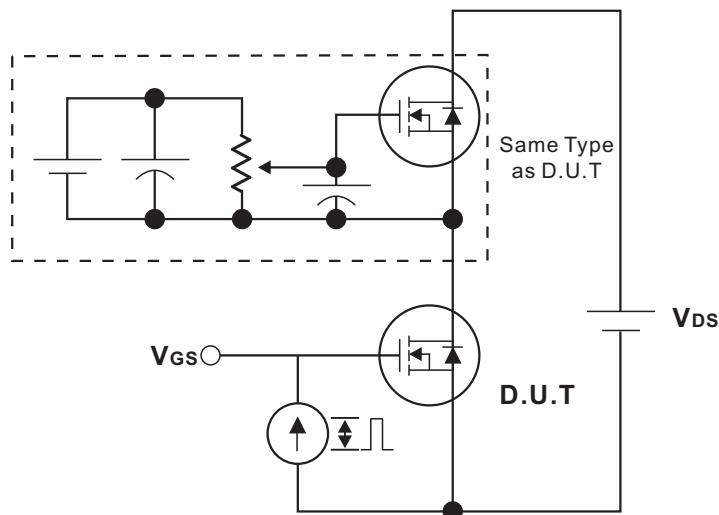
Test Circuits and waveforms



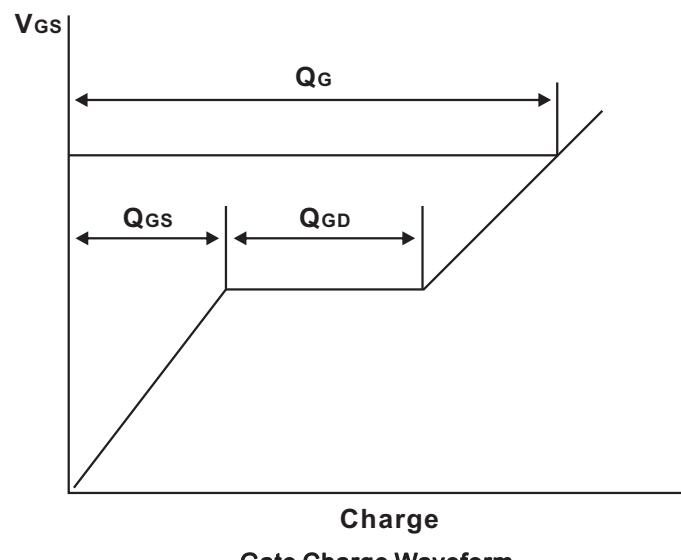
Switching Test Circuit



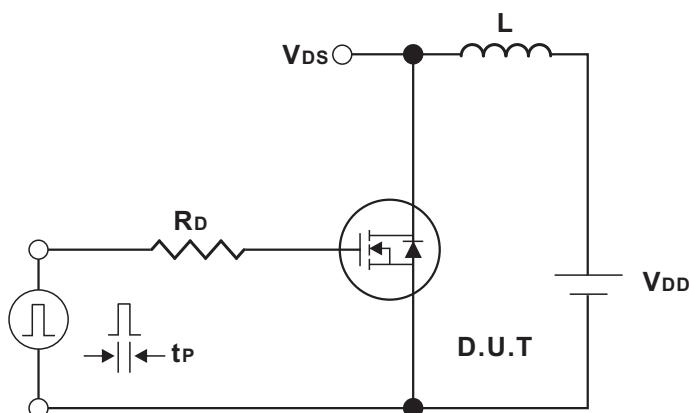
Switching Waveforms



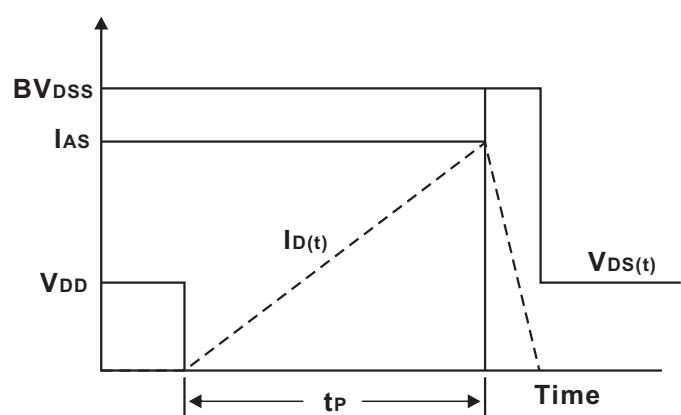
Gate Charge Test Circuit



Gate Charge Waveform



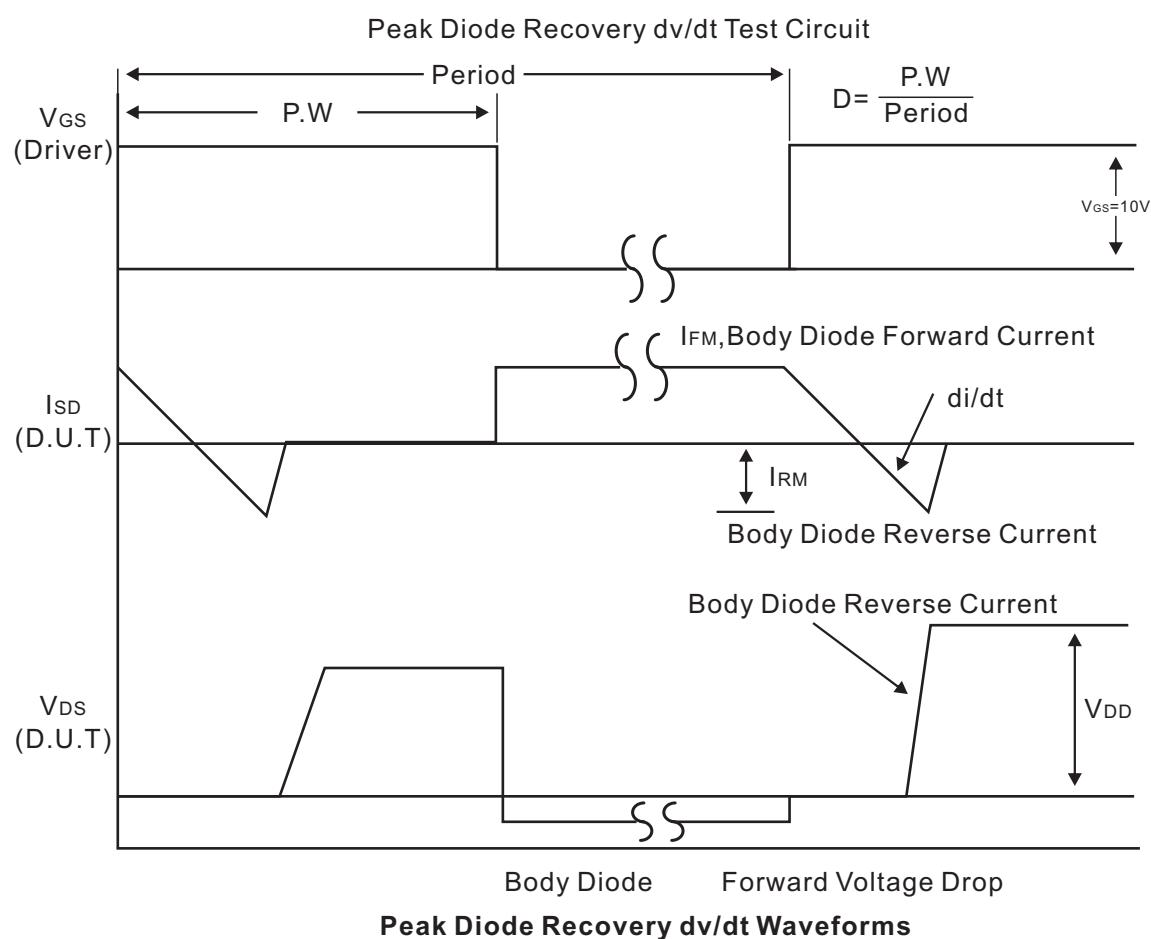
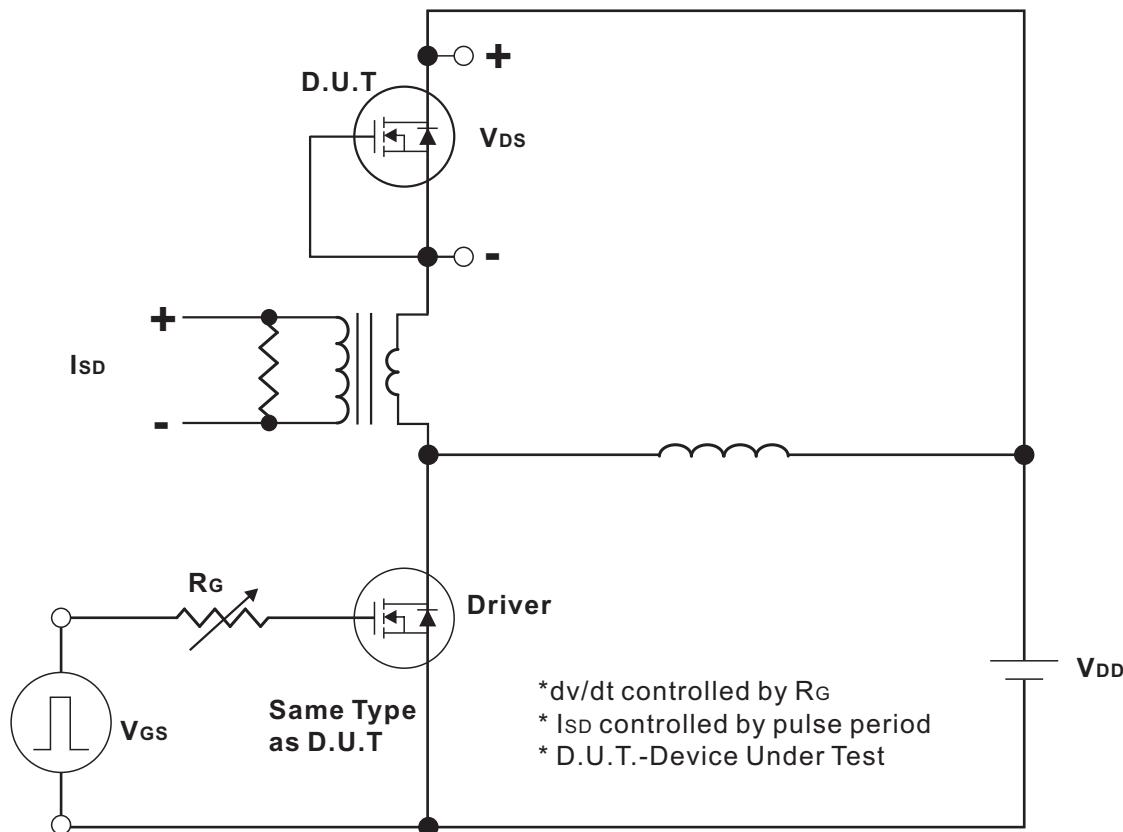
Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms



Test Circuits and waveforms





Typical Characteristics

Fig.1 Output characteristics

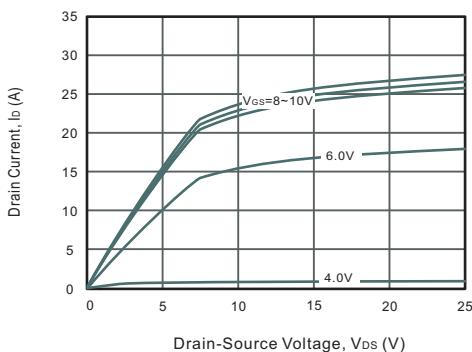


Fig.2 Power Dissipation

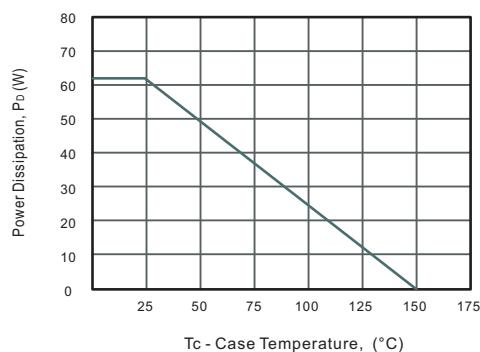


Fig.3 Drain Current Derating

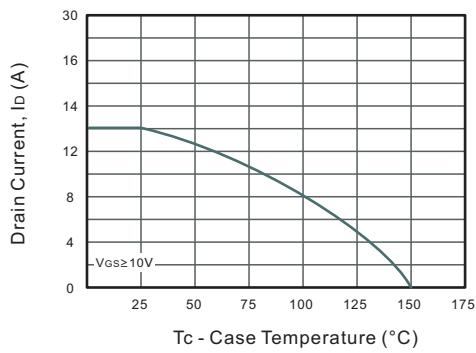


Fig.4 Drain-Source On-Resistance vs. Drain Current

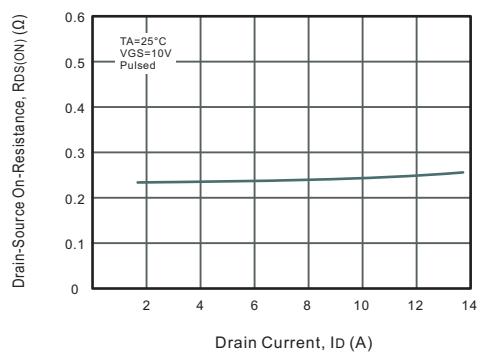


Fig.5 Gate Threshold Voltage vs. Junction Temperature

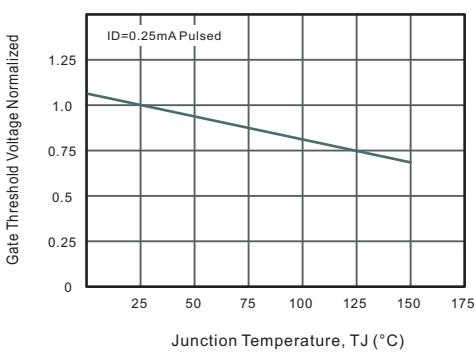


Fig.6 Body-diode Forward Characteristics

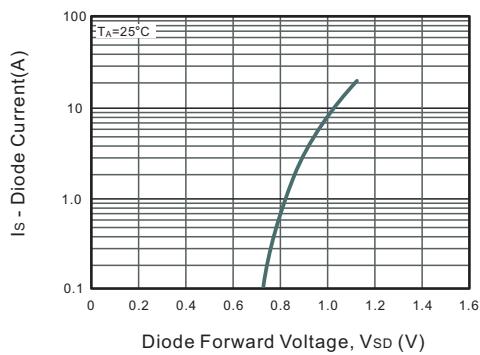


Fig.7 Drain-Source On-Resistance vs. Junction Temperature

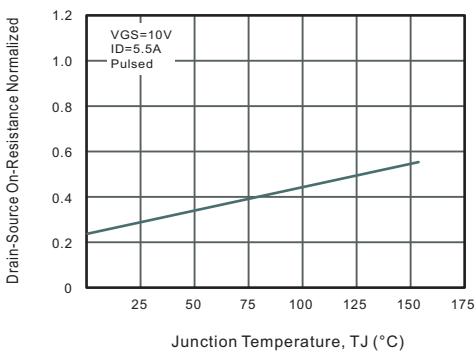
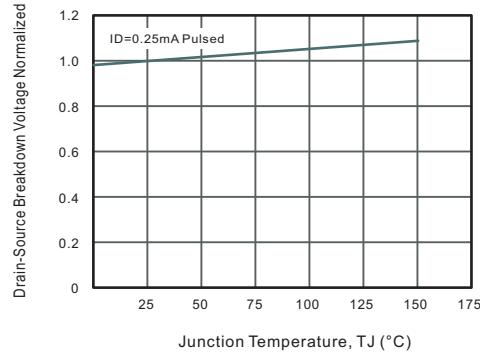


Fig.8 Breakdown Voltage vs. Junction Temperature





Typical Characteristics

Fig.9 Capacitance Characteristics

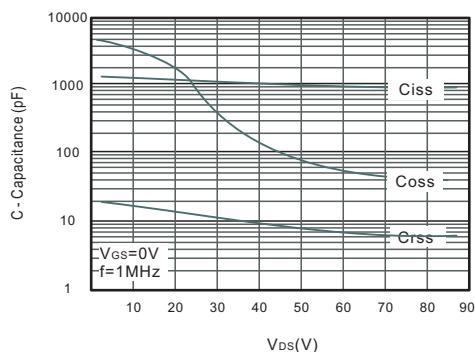


Fig.10 Gate Charge Characteristics

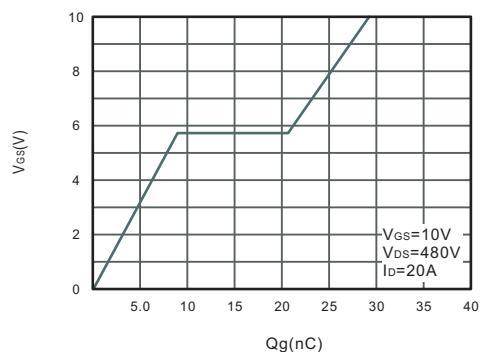


Fig.11 Safe Operating Area

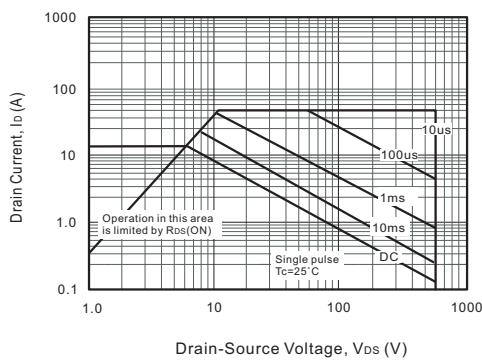
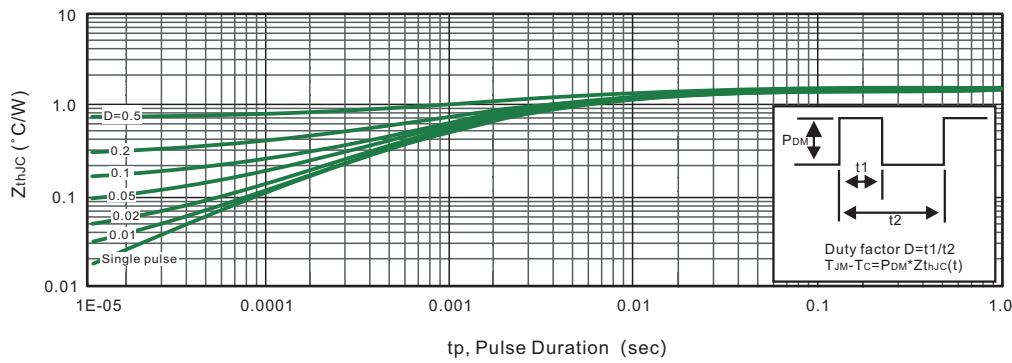
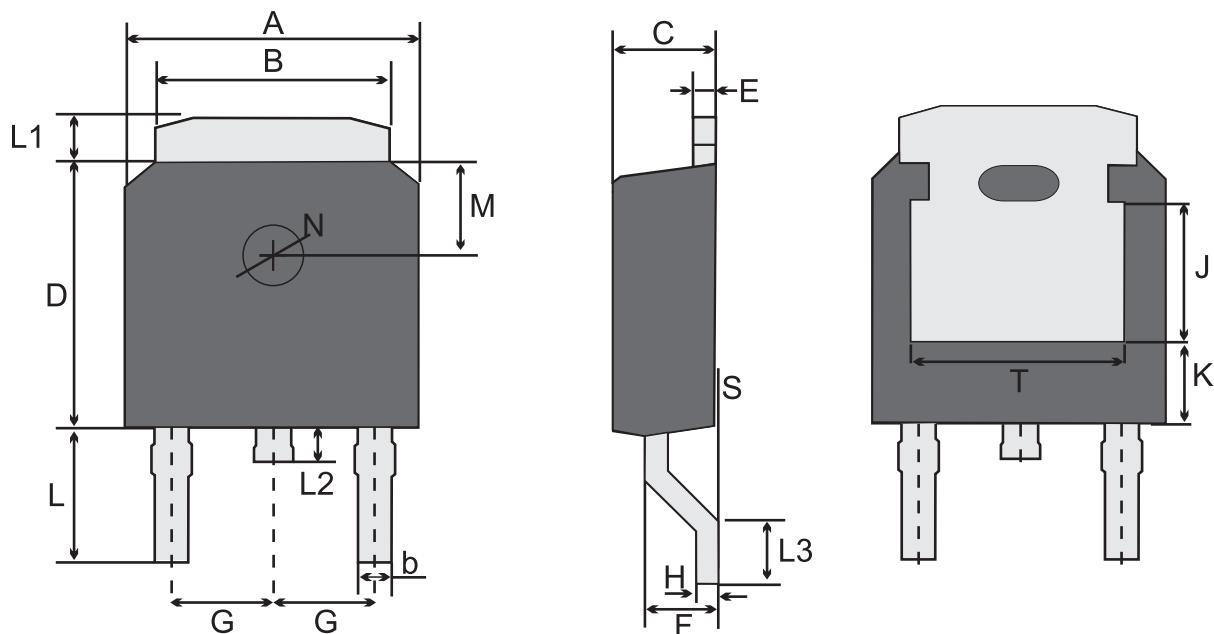


Fig.12 Max. Transient Thermal Impedance





TO-252W(D-PAK) Package Outline Dimensions



TO-252W(D-PAK)Mechanical data

UNIT		A	B	b	C	D	E	F	G	H	L	L1	L2	L3	S	M	N	J	T	K
mm	max	6.7	5.53	0.86	2.5	6.3	0.61	1.87	2.3 typ.	0.55	3.0	1.2	1.0	1.75	0.1	1.8 typ.	1.3 typ.	3.2 ref.	4.83 ref.	1.8 ref.
	typ	6.6	5.33	0.76	2.3	6.1	0.51	1.57		0.50	2.8	1.0	0.8	1.30	0.05					
	min	6.3	5.13	0.66	2.1	5.9	0.41	1.27		0.45	2.6	0.8	0.6	1.0	/					
mil	max	264	218	34	98	248	24	74	91 typ.	22	118	47	39	69	3.9	71 typ.	51 typ.	126 ref.	190 ref.	71 ref.
	typ	260	210	30	91	240	20	62		20	110	39	31	51	2.0					
	min	248	202	26	83	232	16	50		18	102	31	24	39	/					

Marking

Type number	Marking code
D70R280ET	D70R280ET



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